

ABSTRACT OF THE DISCLOSURE

[0080] Platinum, silver and gold solder compositions for repairing, assembling, or sizing jewelry. Platinum compositions having about 90% to about 95% by weight platinum. Silver compositions having at least 92.5% by weight silver. Gold solder compositions having about 25% to about 91.6% gold. The platinum and silver solder compositions further consisting of about 8.3% to about 75% by weight of an alloy consisting essentially of gallium, indium and copper in respective ratios of 6:3:1. The gold solder compositions further consisting of about 2% to about 14% by weight of an alloy consisting essentially of gallium, indium, and copper in respective ratios of 6:3:1. The melting temperature ranges of the respective solder compositions are from about 1300°C to about 1500°C for platinum, from about 1000° F to about 1400° F for silver, and from about 1100° F to about 1550° F.